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# AMD 2014 Mobile APUs to Deliver Leaps in Performance and Battery Life in Tablets, 2-in-1s and Notebooks

## New Designs Target Highest Performance and Best Graphics for Fanless Designs

SAN JOSE, CA -- (Marketwired) -- 11/13/13 -- [AMD](#) (NYSE: AMD), building on its leadership in graphics and gaming, announced its 2014 mobile Accelerated Processing Unit (APU) product roadmap at the [APU13 Developer Conference](#) today. Raising the performance bar across fanless tablets, 2-in-1s and ultrathin notebooks, the APUs codenamed "Mullins" and "Beema" are projected to deliver more than 2x the performance-per-watt of the previous generation(1, 2).

The latest AMD APUs also support Microsoft InstantGo for faster wake times and to ensure data such as email actively refresh in standby. Both new processor families are also the first to integrate an AMD-developed platform security processor based on the ARM® Cortex®-A5 featuring ARM TrustZone® technology for enhanced data security. The new low-power APUs join the previously disclosed high-performance notebook APU, codenamed "Kaveri," in AMD's 2014 mobile lineup.

"AMD is establishing excellent momentum this year in the low-power, mobile computing market and with 'Mullins' and 'Beema' coming in 2014 we are not standing still," said Mark Papermaster, AMD's chief technology officer and senior vice president, during his closing keynote at APU13. "AMD aims to deliver a set of platforms in the first half of next year that will outperform the competition in graphics and total compute performance in fanless tablets, 2-in-1s and ultrathin notebooks."

Both new processor families offer two or four "Puma" CPU cores and AMD Radeon™ graphics on a 28nm system-on-chip (SoC). The new processors are planned to launch in the first half of next year and will be demonstrated at [CES 2014](#) as part of a full suite of AMD products.

### *Supporting Resources*

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the new era of surround computing. AMD solutions enable people everywhere to realize the full potential of their favorite devices and applications to push the boundaries of what is possible. For more information, visit [www.amd.com](http://www.amd.com).

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1. The new 2014 AMD A-Series low power APU platform, codenamed "Mullins," is expected to deliver up to 139 percent better productivity performance per watt when compared to the previous generation "Temash" platform. Testing conducted by AMD Performance Labs on optimized AMD reference systems. PC manufacturers may vary configuration yielding different results. PCMark 8 - Home score divided by TDP (W) is used to simulate productivity performance per watt; the Mullins platform (4.5W) scored 1809 while the Temash platform (8W) scored 1343. AMD "Larne" reference platform system used for both APUs. Temash-based AMD A6-1450 quad-core APU with AMD Radeon™ HD 8250 Graphics, 2x2GB of DDR3-1333MHz RAM (running at 1066MHz), Windows 8.1, 13.200.11.0 - 03-Sep-2013 driver. Pre-production engineering sample of "Mullins" quad-core APU with next generation AMD Radeon graphics (model number TBD), 2x2GB DDR3-1333MHz RAM, Windows 8.1, and unreleased reference driver. MUN-3

2. The new 2014 AMD A-Series mainstream APU platform, codenamed "Beema," is expected to deliver up to 104 percent better productivity performance per watt when compared to the previous generation "Kabini" platform. Testing conducted by AMD Performance Labs on optimized AMD reference systems. PC manufacturers may vary configuration yielding different results. PCMark 8 - Home score divided by TDP (W) is used to simulate productivity performance per watt; the Beema platform (15W) scored 2312 while the Kabini platform (25W) scored 1861. AMD "Larne" reference platform system used for both APUs. Kabini-based AMD A6-5200 quad-core APU with AMD Radeon™ HD 8400 Graphics, 2x2GB of DDR3-1600MHz RAM, Windows 8.1, 13.200.11.0 - 03-Sep-2013 driver. Pre-production engineering sample of "Beema" quad-core APU with next generation AMD Radeon graphics (model number TBD), 2x2GB DDR3-1600MHz RAM, Windows 8.1, and unreleased reference driver. BMN-3

#### Forward-Looking Statement:

This Press Release contains forward-looking statements concerning Advanced Micro Devices, Inc. ("AMD" or the "Company") including, among other things, AMD's 2014 mobile Accelerated Processing Unit (APU) product roadmap, AMD's future products including strategy, the timing, availability, features and functionality of such future products, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act. Forward-looking statements are commonly identified by words such as "would," "may," "expects," "believes," "plans," "intends," "projects," and other terms with similar meaning. Investors are cautioned that the forward-looking statements in this presentation are based on current beliefs, assumptions and expectations, speak only as of the date of this presentation and involve risks and uncertainties that could cause actual results to differ materially from current expectations. Risks include the possibility that that Intel Corporation's pricing, marketing and rebating programs, product bundling, standard setting, new product introductions or other activities may negatively impact the Company's plans; that the Company will require additional funding and may be unable to raise sufficient capital on favorable terms, or at all; that customers stop buying the Company's products or materially reduce their operations or demand for its products; that the Company may be unable to develop, launch and ramp new products and technologies in the volumes that are required

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